L · ·	Hits	Search Text	DB	Time stamp
Number				
1	31	136/203 and (heater and cooler)	USPAT	2003/10/29
				14:53
2	5	(136/203 and (heater and cooler)) and	USPAT	2003/10/29
		(heat adj source)		14:58
3.	613	62/3.3	USPAT	2003/10/29
				15:08
4	325	62/3.3 and (container or box or case)	USPAT	2003/10/29
		•		14:59
5	6	62/3.3 and (semiconductor adj laser)	USPAT	2003/10/29
				15:13
6	142	257/930	USPAT	2003/10/29
				15:30
7	1450	semiconductor adj1 laser adj1 module	USPAT;	2003/10/29
		-	EPO; JPO;	15:31
			DERWENT;	
			IBM TDB	·
8	1450	semiconductor adj1 laser adj1 module	USPAT;	2003/10/29
		•	EPO; JPO;	15:31
			DERWENT;	
			IBM TDB	
9	5	(semiconductor adj1 laser adj1 module)	USPAT;	2003/10/29
		and (thermoelectric adj1 module)	EPO; JPO;	15:34
			DERWENT;	
		•	IBM TDB	
10	44	(semiconductor adj1 laser adj1 module)	USPAT;	2003/10/29
		and (thermoelectric)	EPO; JPO;	15:34
		·	DERWENT;	
		· ,	IBM TDB	

L	Hits	Search Text	DB	Time stamp
Number .				
2	263	136/242	USPAT	2003/10/29
				07:37
3	770	136/230	USPAT	2003/10/29
				07:54
4	219	136/237	USPAT	2003/10/29
				08:02
5	456	136/203	USPAT	2003/10/29
				10:33
6	0	136-200-242.ccls.	USPAT	2003/10/29
			,	10:33
7	3524	136/200-242.ccls.	USPAT	2003/10/29
				10:33
8	8	136/200-242.ccls. and (heat adj1	USPAT	2003/10/29
		radiating adj1 side)	,	10:34
9	7	(136/200-242.ccls. and (heat adj1	USPAT	2003/10/29
		radiating adj1 side)) and (heat adj1		10:41
		absorbing adj1 side)		
10	15	136/242 and (heat adjl sink) and (heat	USPAT	2003/10/29
		adj1 source)		10:46
11	1025	136/200-242.ccls. and (heat absorbing)	USPAT	. 2003/10/29
		and (heat rejecting)		10:47
12	4	136/200-242.ccls. and (heat adj1	USPAT	2003/10/29
`		absorbing) and (heat adj1 rejecting)		10:48
13	112	136/200-242.ccls. and (hot adj1 side) and	USPAT	2003/10/29
		(cold adjl side)	,	11:02
14	1	("4855810").PN.	USPAT	2003/10/29
				11:02